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EFS ID:	2375175				
Application Number:	10551745				
International Application Number:					
Confirmation Number:	5789				
Title of Invention:	Method for the Multi-Stage Production of Diffusion Soldered Connections for Power Components Comprising Semiconductor Chips				
First Named Inventor/Applicant Name:	Edmund Riedl				
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1 Information Disclosure Statement (IDS) Filed		SupplementalInformationDis	33015	no	
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